

AMENDMENT TO THE CLAIMS

Claims 1-16 (Canceled)

17. (New) A process for treating a substrate comprising at least forming an organic layer on said substrate, and reflowing said organic layer at a substrate temperature from 15 degrees to 40 degrees centigrade.

18. (New) The process as set forth in claim 17, in which a deformed organic layer is formed from said organic layer in said reflowing, and said deformed organic layer is thinner than said organic layer.

19. (New) The process as set forth in claim 18, in which said deformed organic layer is equal in thickness to or less than a third of the thickness of said organic layer.

20. (New) The process as set forth in claim 17, in which chemical solution is penetrated into said organic layer so as to dissolve part of said organic layer, thereby reflowing said organic layer.

21. (New) The process as set forth in claim 17, in which chemical solution is penetrated into said organic layer so as to dissolve part of said organic layer for the reflowing, and heat is applied to said organic layer so as to reflow part of said organic layer.

22. (New) The process as set forth in claim 20, in which said organic layer is exposed to a gaseous mixture of organic solution containing at least organic solvent for making said chemical solution penetrate into said organic layer.

23. (New) The process as set forth in claim 21, in which said organic layer is exposed to a high-temperature ambient at 50-300 degrees centigrade for applying the heat.

24. (New) The process as set forth in claim 22, in which said gaseous mixture ranges from 15 degrees to 40 degrees centigrade.

25. (New) The process as set forth in claim 20, in which a deformed organic layer produced from said organic layer is thinner than said organic layer after the reflowing through the dissolution.

26. (New) The process as set forth in claim 20, in which said chemical solution or said organic solution containing said organic solvent comprises an organic solution containing at least organic solvent selected from the group consisting of alcohols expressed by a general formula of R-OH, alkoxyalcohols, ethers expressed by a general formula of R-O-R, Ar-O-R and Ar-O-Ar, esters, ketones, glycols, alkylene glycols, and glycol ethers where R is an alkyl group or a substituted alkyl group and Ar is Phenyl group or aromatic ring except said phenyl group.

27. (New) The process as set forth in claim 17, in which said organic layer comprises a resist

layer.

28. (New) The process as set forth in claim 18, in which chemical solution is penetrated into said organic layer so as to dissolve part of said organic layer, thereby reflowing said organic layer.

29. (New) The process as set forth in claim 19, in which chemical solution is penetrated into said organic layer so as to dissolve part of said organic layer, thereby reflowing said organic layer.

30. (New) The process as set forth in claim 18, in which chemical solution is penetrated into said organic layer so as to dissolve part of said organic layer for the reflowing, and heat is applied to said organic layer so as to reflow part of said organic layer.

31. (New) The process as set forth in claim 19, in which chemical solution is penetrated into said organic layer so as to dissolve part of said organic layer for the reflowing, and heat is applied to said organic layer so as to reflow part of said organic layer.

32. (New) The process as set forth in claim 21, in which said organic layer is exposed to a gaseous mixture of organic solution containing at least organic solvent for making said chemical solution penetrate into said organic layer.

33. (New) The process as set forth in claim 21, in which a deformed organic layer produced

from said organic layer is thinner than said organic layer after the reflowing through the dissolution.

34. (New) The process as set forth in claim 22, in which a deformed organic layer produced from said organic layer is thinner than said organic layer after the reflowing through the dissolution.

35. (New) The process as set forth in claim 23, in which a deformed organic layer produced from said organic layer is thinner than said organic layer after the reflowing through the dissolution.

36. (New) The process as set forth in claim 24, in which a deformed organic layer produced from said organic layer is thinner than said organic layer after the reflowing through the dissolution.

37. (New) The process as set forth in claim 21, in which said chemical solution or said organic solution containing said organic solvent comprises an organic solution containing at least organic solvent selected from the group consisting of alcohols expressed by a general formula of $R-OH$, alkoxyalcohols, ethers expressed by a general formula of $R-O-R$, $Ar-O-R$ and $Ar-O-Ar$, esters, ketones, glycols, alkylene glycols, and glycol ethers where R is an alkyl group or a substituted alkyl group and Ar is Phenyl group or aromatic ring except said phenyl group.

38. (New) The process as set forth in claim 22, in which said chemical solution or said organic solution containing said organic solvent comprises an organic solution containing at least organic solvent selected from the group consisting of alcohols expressed by a general formula $R-OH$, alkoxyalcohols, ethers expressed by a general formula of $R-O-R$, $Ar-O-R$ and $Ar-O-Ar$, esters, ketones, glycols, alkylene glycols, and glycol ethers where R is an alkyl group or a substituted alkyl group and Ar is Phenyl group or aromatic ring except said phenyl group.

39. (New) The process as set forth in claim 18, in which said organic layer comprises a resist layer.

40. (New) The process as set forth in claim 19, in which said organic layer comprises a resist layer.

41. (New) The process as set forth in claim 20, in which said organic layer comprises a resist layer.

42. (New) The process as set forth in claim 21, in which said organic layer comprises a resist layer.

43. (New) The process as set forth in claim 22, in which said organic layer comprises a resist layer.

44. (New) The process as set forth in claim 23, in which said organic layer comprises a resist

layer.

45. (New) The process as set forth in claim 24, in which said organic layer comprises a resist layer.

46. (New) The process as set forth in claim 25, in which said organic layer comprises a resist layer.

47. (New) The process as set forth in claim 26, in which said organic layer comprises a resist layer.